



This document contains information considered proprietary, and shall not be reproduced wholly or in part, nor disclosed to others without specific written permission.

HARDWARE NAME:MAX17558_EVKIT_A

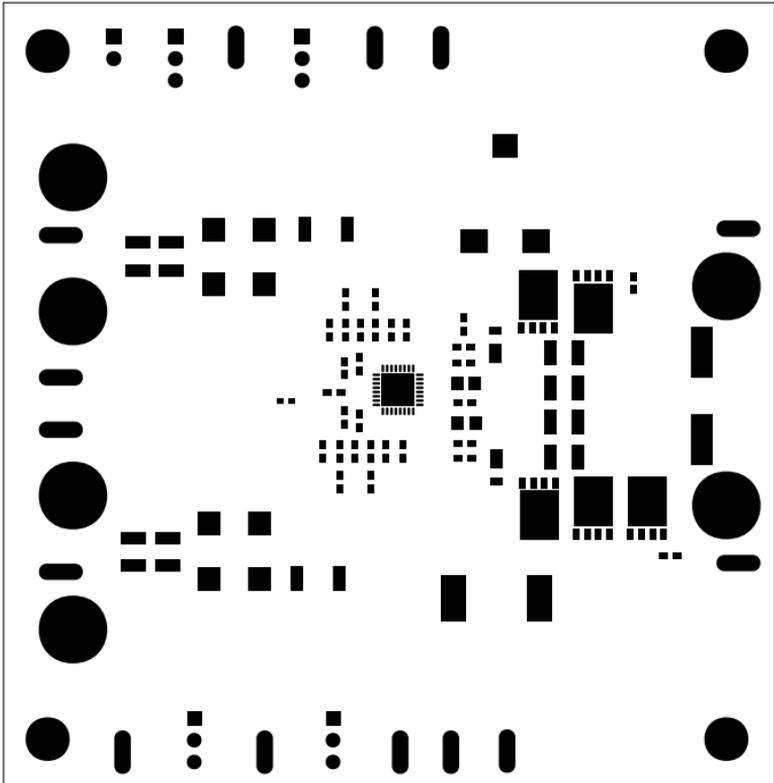
HARDWARE NUMBER:

ENGINEER:MURALI MALLA

DESIGNER:MANIKANDAN SELVAM

DATE: 11/28/2014

ODB++/GERBER: MASK_TOP





This document contains information considered proprietary, and shall not be reproduced wholly or in part, nor disclosed to others without specific written permission.

HARDWARE NAME:MAX17558_EVKIT_A

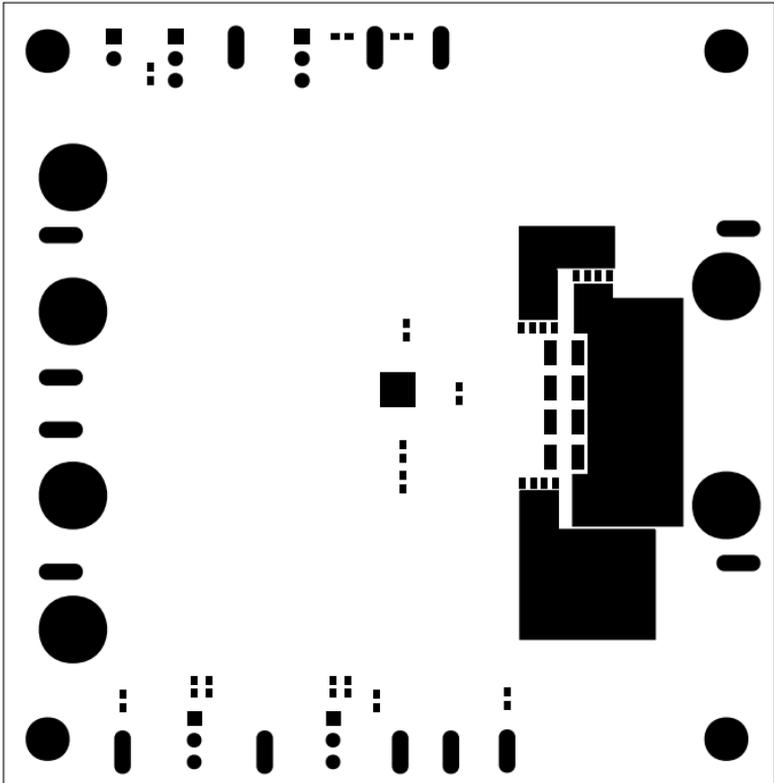
HARDWARE NUMBER:

ENGINEER:MURALI MALLA

DESIGNER:MANIKANDAN SELVAM

DATE: 11/28/2014

ODB++/GERBER: MASK_BOT



REVISIONS			
REV	DESCRIPTION	APPROVED	DATE
P3	INITIAL RELEASE	MM	06/06/14
A	PRODUCTION RELEASE	MM	11/28/14

- NOTES:
- UNLESS OTHERWISE SPECIFIED
 - DIMENSIONS ARE IN INCHES (EXCEPT WHERE NOTED).
 - MATERIAL: [USE CHECKED ITEMS FOR MATERIAL]
 - BOARD MATERIAL:
 - FR4 (RHS COMPLIANT) OR EQUIVALENT
 - ISOLA-FR408HR
 - NELCO-4000-13 OR EQUIVALENT
 - 370HR (RHS COMPLIANT) OR EQUIVALENT
 - ROGERS 4350B/FR408HR
 - ROGERS 4002C/FR408HR
 - OTHER _____
 - THE PCB SHALL BE FABRICATED TO IPC-6012, TYPE X, CLASS 2.
 - WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2, CURRENT REVISIONS.
 - BOARD MATERIAL & CONSTRUCTION SHALL MEET THE REQUIREMENTS OF UL796 WITH FLAMMABILITY RATING OF 94V-0.
 - OVERALL BOARD THICKNESS REFER TO LAMINATION DIAGRAM. TOLERANCE APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES. IT IS TO BE MEASURED FROM TOP PCB METAL TO BOTTOM PCB METAL UNLESS OTHERWISE SPECIFIED.
 - BOW & TWIST NOT TO EXCEED 0.0075 IN. (0.15%) PER LINEAR INCH. BOW & TWIST SHOULD BE MEASURED PER IPC-TM-650, METHOD 2.4.22.
- TOOLING: [USE CHECKED ITEMS FOR TOOLING]
- PHOTO ETCH CIRCUITRY PER ENCLOSED GERBER R5274X OR ODB++ FORMAT FILE. DRILL LOCATION AND SIZE CONTROLLED BY EXCELLON CNC DRILL FILE.
 - IF STATED IN THE LAMINATION DIAGRAM, THE DIELECTRIC THICKNESS OF ANY CONTROLLED IMPEDANCE LAYER IS FOR REFERENCE ONLY. FINAL ACCEPTANCE SHALL BE DETERMINED BY THESE LAYERS HAVING A CHARACTERISTIC IMPEDANCE OF +/-10% OHMS AS STATED IN THE LAMINATION DIAGRAM. THE VENDOR CAN MAKE ADJUSTMENTS AS LONG AS THE STATED IMPEDANCE AND OVERALL BOARD THICKNESS IS MAINTAINED. ANY ADJUSTMENT MADE TO TRACE WIDTH OR SPACING MUST HAVE PRIOR WRITTEN APPROVAL FROM MAXIM.
 - ALL TRACES FILLETED OPTION TO ENHANCE RELIABILITY AT PAD JUNCTIONS WHERE SPACING PERMITS. UNLESS OTHERWISE SPECIFIED:
 - FILLETED
 - NOT FILLETED
 - LAYER TO LAYER REGISTRATIONS SHALL BE WITHIN .003 INCHES. LEGEND TO LEGEND +/- 0.007 INCHES
- FINISH: [USE CHECKED ITEMS FOR PLATING]
- PLATING SPECIFICATION:
 - STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (1 OZ). THE FINISH COPPER WEIGHT IS (1 OZ). FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (1 OZ) AS A STARTING WEIGHT THE STARTING WEIGHT CAN BE (0.5 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (1 OZ) UNLESS OTHERWISE SPECIFIED.
 - STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (1 OZ). THE FINISH COPPER WEIGHT IS (2 OZ). FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (1 OZ) AS A STARTING WEIGHT, THE STARTING WEIGHT CAN BE (0.5 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (2 OZ), UNLESS OTHERWISE SPECIFIED.
 - STARTING COPPER WEIGHT FOR OUTER LAYERS TO BE (2 OZ). THE FINISH COPPER WEIGHT IS (2 OZ) MINIMUM. FOR OUTER LAYERS WHERE SPACING PREVENTS THE USE OF (2 OZ) AS A STARTING WEIGHT, THE STARTING WEIGHT CAN BE (<2 OZ) AS LONG AS THE FINISH COPPER WEIGHT IS (2 OZ), UNLESS OTHERWISE SPECIFIED.
 - OTHER _____
 - CHECK ALL THAT APPLY
 - FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 3-8 MICRO INCHES OVER 100 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL.
 - LEAD FREE AND RHS COMPLIANT OR EQUIVALENT LEAD FREE PLATING
 - ELECTRODEPOSITED HARD GOLD PLATE, TYPE 1 (99.7% MIN GOLD), GRADE C (KNOOP HARDNESS 130-200), CLASS 1 (50-100 MICRO INCHES THICK) IN ACCORDANCE WITH MIL-G-45204C. GENERAL SURFACING REQUIREMENTS MUST MEET ANSI/IPC-A-600(CURRENT REV) SECTION 4.0. CLASS 3 (50-100 MICROINCHES THICK) OVER ELECTRODEPOSITED NICKEL PLATE IN ACCORDANCE WITH ANSI/IPC-A-600D, SECTION 4.0, CLASS 3 (200-600 MICROINCHES THICK).
 - FINISH CONDUCTOR SURFACES: IMMERSION GOLD, 2-5 MICRO INCHES OVER 118-236 MICRO INCHES MINIMUM OF ELECTROLESS NICKEL.
 - FINGERS TO BE GOLD PLATED.
 - OTHER _____
 - DRILL SIZES ARE FINISHED HOLE SIZES. ALL HOLES SHALL BE LOCATED WITHIN .005 DTP. MINIMUM BARREL PLATING OF .001 IN. PLATED HOLES SHALL NOT BE ROUGH OR IRREGULAR SO AS TO HINDER PROPER SOLDER WICKING.
 - CHECK ALL THAT APPLY
 - GREEN SOLDERMASK OVER BARE COPPER/BARE GOLD (BOTH SIDES) WITH LIQUID PHOTO IMAGEABLE INK (LPI) PER ARTWORK.
 - GREEN TAIYO PSR-4000
 - OTHER _____
 - CHECK ALL THAT APPLY
 - APPLY SILKSCREEN USING A NON-CONDUCTIVE, WHITE EPOXY BASED INK PER ARTWORK.
 - OTHER _____
 - VENDOR LOGO & DATE CODE REQUIRED IN INK ON BOTTOM SIDE ONLY. DATE CODE FORMAT MUST BE YYYY ONLY
- TESTING:
- FINAL ELECTRICAL TEST TO BE PERFORMED USING PROVIDED IPC-D-356A NETLIST OR ODB++ FORMAT FILE. (REQUIRED UNLESS OTHERWISE SPECIFIED IN QUOTE) THE PCB SHALL HAVE A VERIFICATION STAMP.
 - A TIME DOMAIN REFLECTOMETER REPORT FOR EACH IMPEDANCE CONTROLLED LAYER AND A CERTIFICATE OF COMPLIANCE SHALL BE PROVIDED BY VENDOR AT TIME OF SHIPMENT.
- MISCELLANEOUS:
- FOR ALL DRILL INFORMATION REFER TO DRILL CHART.
 - NON-CONDUCTIVE EPOXY FILL AND CAP ALL 0.XXXX INCH DRILLED VIAS.
 - SILVER FILL AND CAP ALL 0.XXXX INCH DRILLED VIAS.
 - IF PRESENT, ALL MICRO-VIAS LESS THAN 0.008 INCHES FMS WHEN USED AS VIP (VIA IN PAD) OR STACKED TO BE PLATED SHUT WITH COPPER, UNLESS OTHERWISE SPECIFIED.
 - FINISHED SURFACE CONTACTS AND FILLED VIAS TO BE FREE OF ANY PITS, SCRATCHES PROBE MARKS OR OTHER DEFORMITIES THAT COULD EFFECT THE APPEARANCE AND PERFORMANCE OF THE CONTACT SURFACE. CONTACTS ARE TO BE AS FLAT AS POSSIBLE, NOT TO EXCEED +/- 0.001" OF FLATNESS.
 - THEFTING:
 - SUPPLIER MAY ADD THEFTING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.
 - SUPPLIER MAY NOT ADD THEFTING TO COMPENSATE FOR LOW COPPER DENSITY AREAS ON THIS DESIGN.
 - PENUT
 - PENUTS TO BE INSTALLED BY SUPPLIER.
 - PENUTS NOT TO BE INSTALLED BY SUPPLIER.
 - NOT APPLICABLE
 - INTENTIONAL SHORTS
 - THERE ARE INTENTIONAL SHORTS ON THIS DESIGN. SEE SHORT REPORT SUPPLIED WITH FAB DATA.

LAYER	50 OHM TRACE / SPACE	65 OHM TRACE / SPACE	100 OHM TRACE / SPACE	75 OHM TRACE / SPACE
TOP	-	-	-	-
X	-	-	-	-
X	-	-	-	-
BOTTOM	-	-	-	-

NOTE: DO NOT EDIT THIS TABLE MANUALLY. USE IMPEDANCE TABLE GENERATOR FROM MAXIMTOOLS.

maxim integrated

WORKING FILE: MAXI7558_EVKIT_A

DESIGNED BY: MURALI MALLA

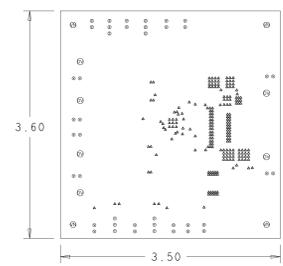
DATE: 11/28/2014

DESIGNED BY: MURALI MALLA

DATE: 11/28/2014

DESIGNED BY: MURALI MALLA

DATE: 11/28/2014



LAYER NUMBER	LAYER NAME	FINISHED CU WEIGHT (OZ)	DIELECTRIC THICKNESS (in.)	DIELECTRIC MATERIAL
1	TOP	2	TBD	FR4 (RHS)/E01V
2	SGND	1	TBD	FR4 (RHS)/E01V
3	P0ND	1	TBD	FR4 (RHS)/E01V
4	BOTTOM	2	TBD	FR4 (RHS)/E01V

THE FINISHED PCB THICKNESS TO BE: 0.0625" +/- 0.010"

FIGURE	SIZE	TOLERANCE	PLATED	QTY	NOTES
Δ	12.0	+3.0/-10.0	PLATED	208	
⊖	39.37	+3.0/-3.0	PLATED	28	
⊖	43.31	+3.0/-3.0	PLATED	6	
⊖	45.28	+3.0/-3.0	PLATED	8	
⊖	125.0	+3.0/-3.0	PLATED	4	
⊖	212.6	+3.0/-3.0	PLATED	6	

TOLERANCES UNLESS OTHERWISE SPECIFIED		THE INFORMATION CONTAINED IN THIS DOCUMENT IS PROPRIETARY TO MAXIM. THE INFORMATION IN THIS DOCUMENT IS NOT TO BE SHOWN, REPRODUCED, OR DISCLOSED TO ANYONE OUTSIDE OF MAXIM WITHOUT PRIOR WRITTEN PERMISSION FROM MAXIM.		<p>maxim integrated™</p> <p>TITLE: FABRICATION DWG. MAXI7558_EVKIT_A</p>
FRACTIONS	DECIMALS	ANGLES		
$\frac{XX}{YY}$ $\frac{.XX}{YY}$	$.XX$ $.XX$	01 $.005$	$\frac{XX}{YY}$ $\frac{.XX}{YY}$	DRAWN BY: MANIKANDAN S DATE: 11/28/14 CHECKED BY: MURALI MALLA DATE: 11/28/14 APPR. BY: MURALI MALLA DATE: 11/28/14 APPR. BY: EDMON DIMLA DATE: 11/28/14
MATERIAL:	SEE NOTES	FINISH:	SEE NOTES	SIZE: DRAWING NO. NOT TO SCALE TEMPLATE REV 1.7 SHEET 1 OF 1



This document contains information considered proprietary, and shall not be reproduced wholly or in part, nor disclosed to others without specific written permission.

HARDWARE NAME:MAX17558_EVKIT_A

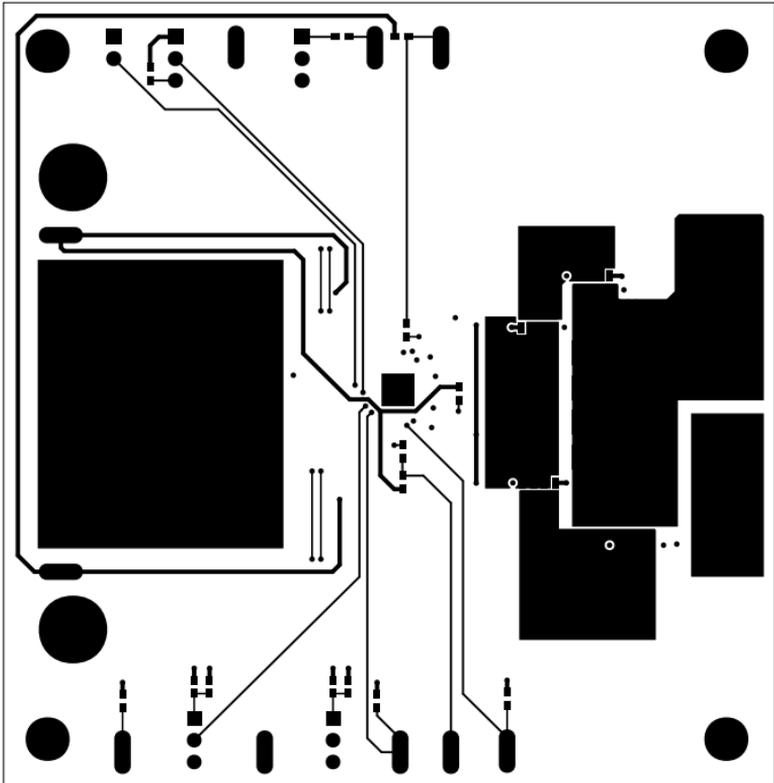
HARDWARE NUMBER:

ENGINEER:MURALI MALLA

DESIGNER:MANIKANDAN SELVAM

DATE: 11/28/2014

ODB++/GERBER: BOTTOM





This document contains information considered proprietary, and shall not be reproduced wholly or in part, nor disclosed to others without specific written permission.

HARDWARE NAME:MAX17558_EVKIT_A

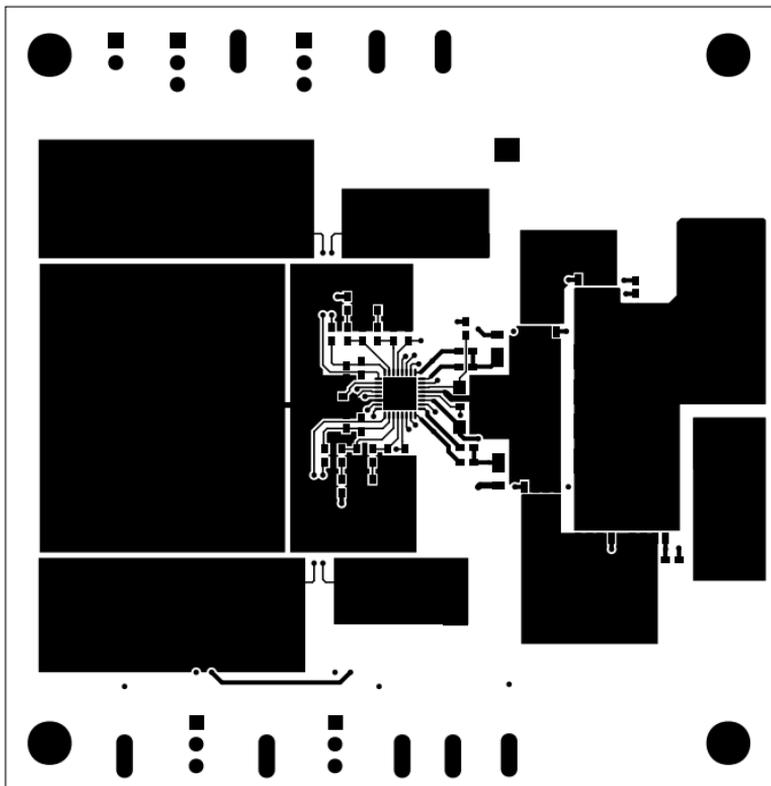
HARDWARE NUMBER:

ENGINEER:MURALI MALLA

DESIGNER:MANIKANDAN SELVAM

DATE: 11/28/2014

ODB++/GERBER: TOP





This document contains information considered proprietary, and shall not be reproduced wholly or in part, nor disclosed to others without specific written permission.

HARDWARE NAME:MAX17558_EVKIT_A

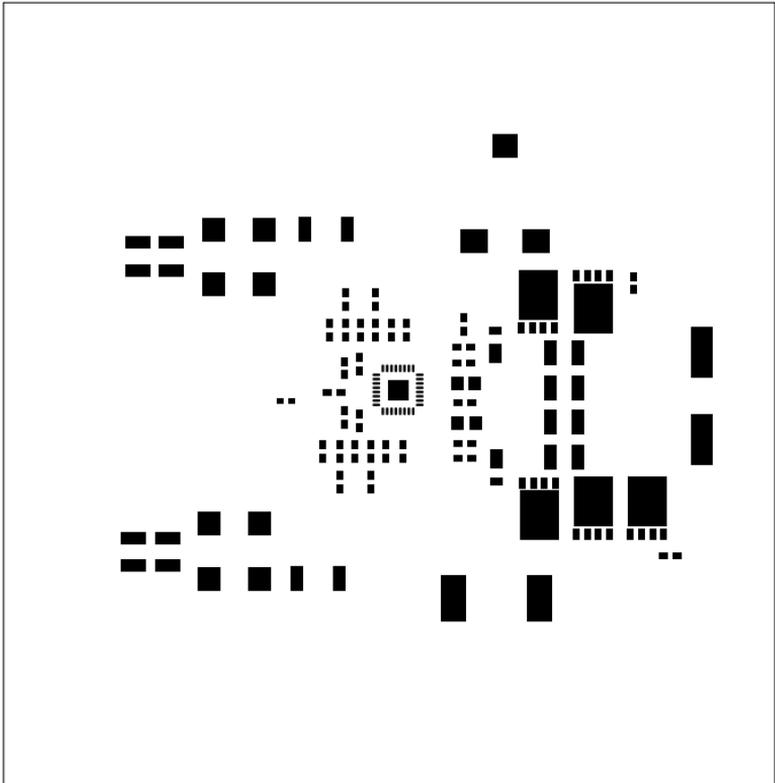
HARDWARE NUMBER:

ENGINEER:MURALI MALLA

DESIGNER:MANIKANDAN SELVAM

DATE: 11/28/2014

ODB+:/GERBER: PASTE_TOP





This document contains information considered proprietary, and shall not be reproduced wholly or in part, nor disclosed to others without specific written permission.

HARDWARE NAME:MAX17558_EVKIT_A

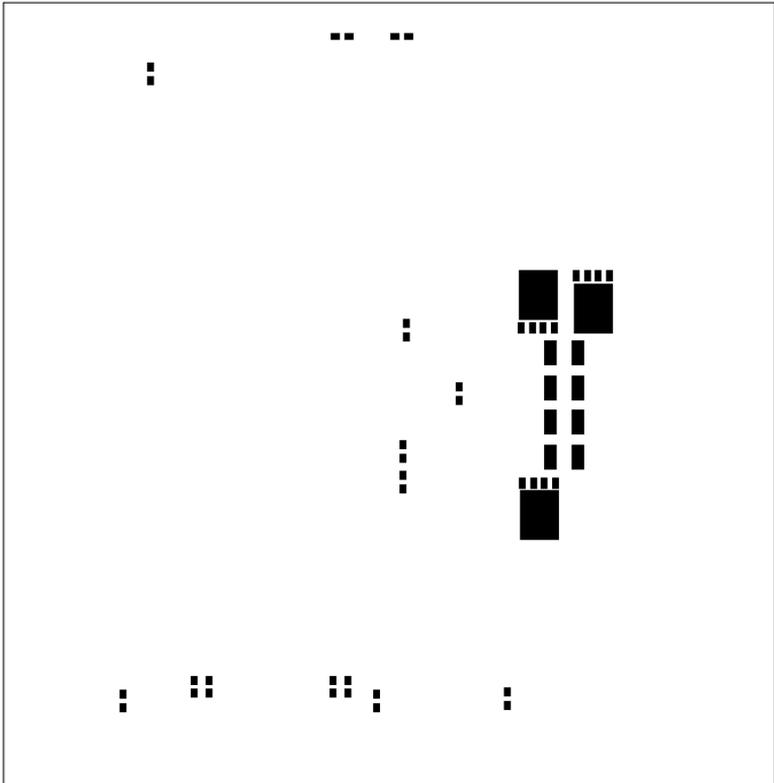
HARDWARE NUMBER:

ENGINEER:MURALI MALLA

DESIGNER:MANIKANDAN SELVAM

DATE: 11/28/2014

ODB++/GERBER: PASTE_BOT





This document contains information considered proprietary, and shall not be reproduced wholly or in part, nor disclosed to others without specific written permission.

HARDWARE NAME:MAX17558_EVKIT_A

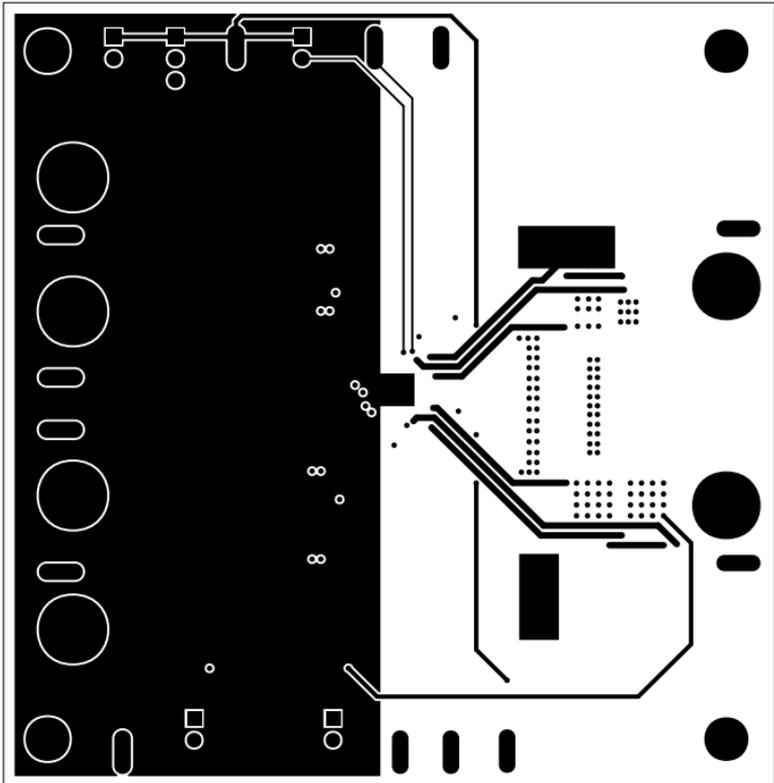
HARDWARE NUMBER:

ENGINEER:MURALI MALLA

DESIGNER:MANIKANDAN SELVAM

DATE: 11/28/2014

ODB++/GERBER: SGND





This document contains information considered proprietary, and shall not be reproduced wholly or in part, nor disclosed to others without specific written permission.

HARDWARE NAME:MAX17558_EVKIT_A

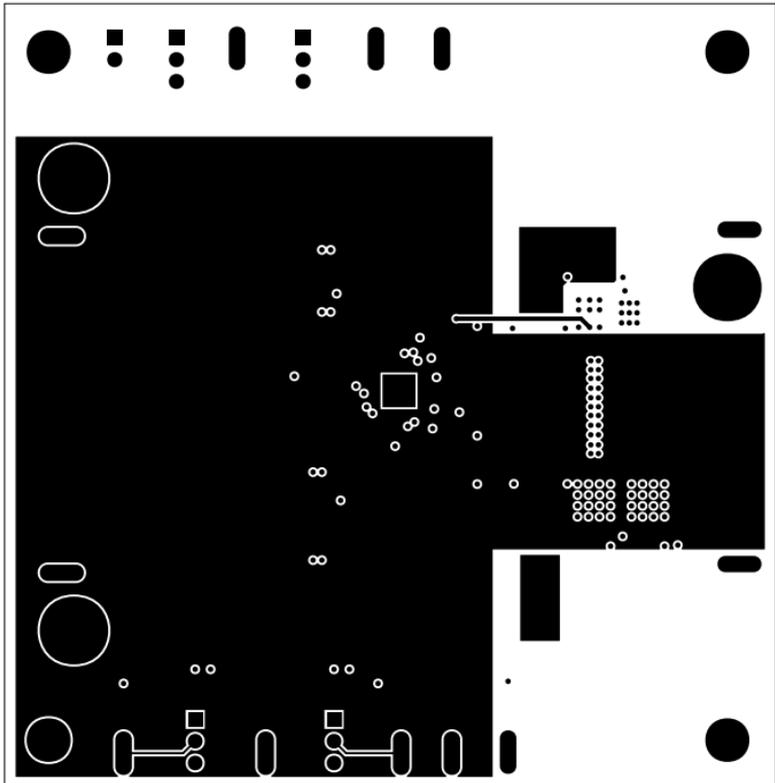
HARDWARE NUMBER:

ENGINEER:MURALI MALLA

DESIGNER:MANIKANDAN SELVAM

DATE: 11/28/2014

ODB++/GERBER: PGND





This document contains information considered proprietary, and shall not be reproduced wholly or in part, nor disclosed to others without specific written permission.

HARDWARE NAME:MAX17558_EVKIT_A

HARDWARE NUMBER:

ENGINEER:MURALI MALLA

DESIGNER:MANIKANDAN SELVAM

DATE: 11/28/2014

ODB+//GERBER: SILK_TOP

